



LEDTECH ELECTRONICS CORP.

NANYA ROAD,MUGANG ZHAOQING
CITY GUANGDONG CHINA.

TEL:86-758-2875541,2870651,2877464,2876185,2877017

FAX:86-758-2878014

[Http://www.ledtech.com.tw](http://www.ledtech.com.tw)

SPECIFICATION

PART NO. : LT1K63-6L-UEE3-SA8-Z

3.2 x 2.8mm SMD TYPE



Approved by

Checked by

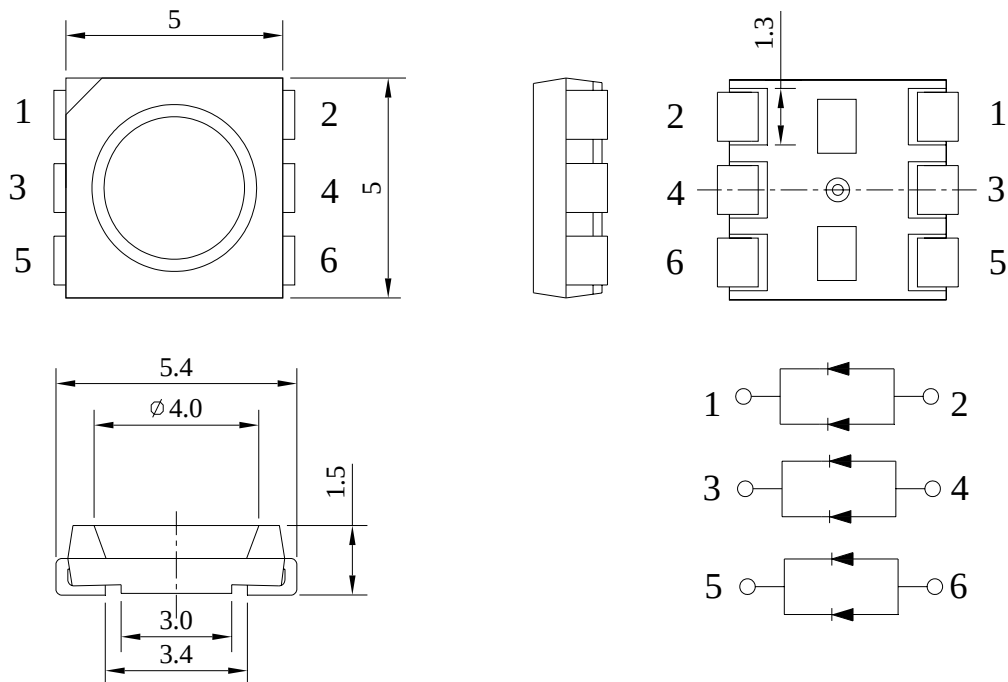
Prepared by

Tung

Lian

Yuan

Package Dimensions



Notes:

1. All dimensions are in mm.
2. Tolerance is $\pm 0.25\text{mm}$ unless otherwise noted.

Description

Part No.	LED Chip		Lens Color
	Material	Color Coordinates	
LT1K63-6L-UEE3-SA8-Z	InGaN/Sapphire	X=0.31 Y=0.30	Water Clear

Absolute Maximum Ratings at Ta=25 °C

Parameter	Symbol	Rating	Unit
Power Dissipation ★	P _d	120	mW
Reverse Voltage ★	V _r	5	V
D.C. Forward Current ★	I _f	30	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.) ★	I _f (Peak)	100	mA
Operating Temperature Range	T _{opr.}	-40 to +100	°C
Storage Temperature Range	T _{stg.}	-40 to +100	°C
Soldering Temperature	T _{sld.}	Reflow Soldering: 260°C for 10 sec. Hand Soldering: 350°C for 3 sec.	
Electric Static Discharge Threshold (HBM) ★	ESD	6000	V

★ The value are based on 1 die performance.

Electrical and Optical Characteristics:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity ★2	I _v	I _f =40mA★3	2750	5800		mcd
Luminous Flux ★2	Φ _v	I _f =40mA★3		9580		mlm
Forward Voltage★3	V _f	I _f =40mA★3		3.2	4.0	V
CIE Chromaticity Coordinates : X Axis ★2	X	I _f =40mA★3		0.31		
CIE Chromaticity Coordinates : Y Axis ★2	Y	I _f =40mA★3		0.30		
Reverse Current ★1	I _r	V _r =5V★3			50	μA
Viewing Angle ★2	2 θ 1/2	I _f =40mA★3		120		deg

Notes: 1.The datas tested by IS tester.

2. Customer's special requirements are also welcome.

3. ★1 For each die

4. ★2 When all LED dies are operated simultaneously.

5. ★3 For one circuit

Typical Electrical/Optical Characteristic Curves (25°C Ambient Temperature Unless Otherwise Noted)

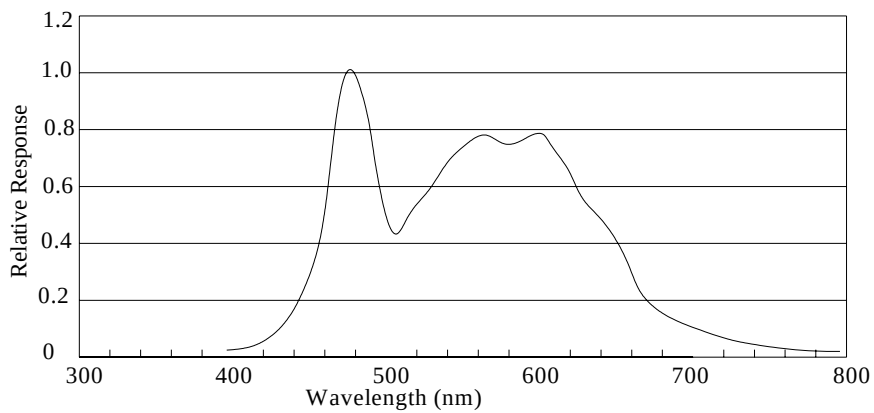
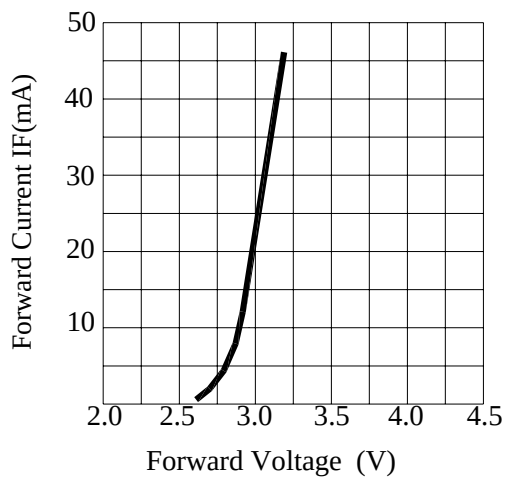
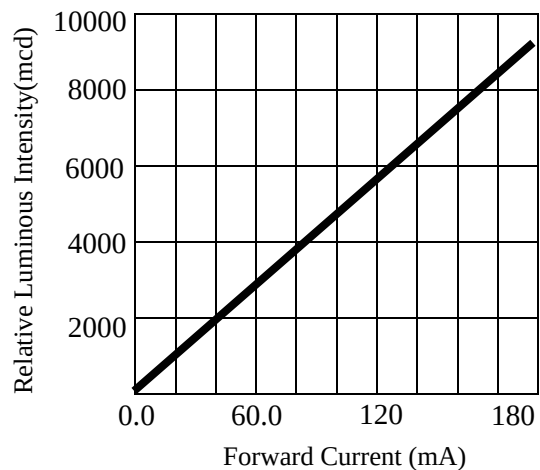


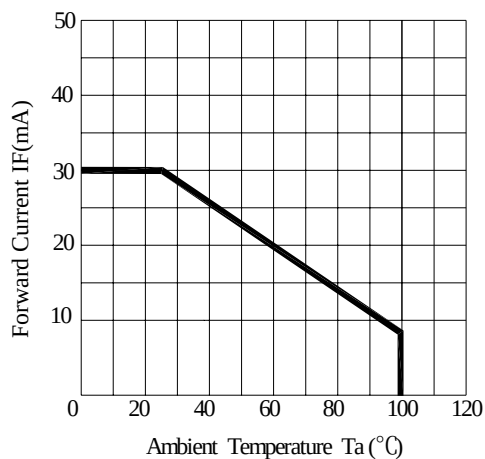
Fig.1 RELATIVE LUMINOUS INTENSITY



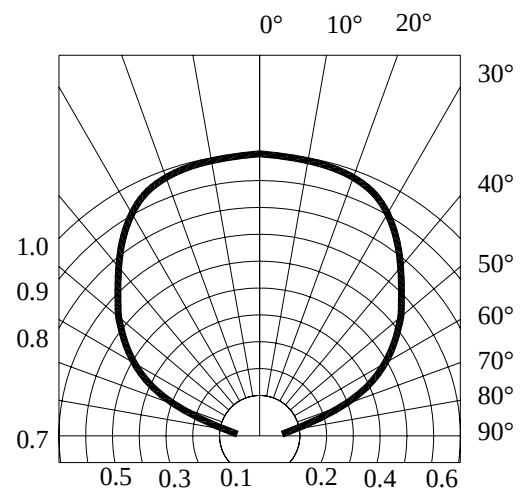
Forward Current VS. Forward Voltage



Forward Current VS. Luminous Intensity



Ambient Temperature VS. Forward Current



Radiation Diagram

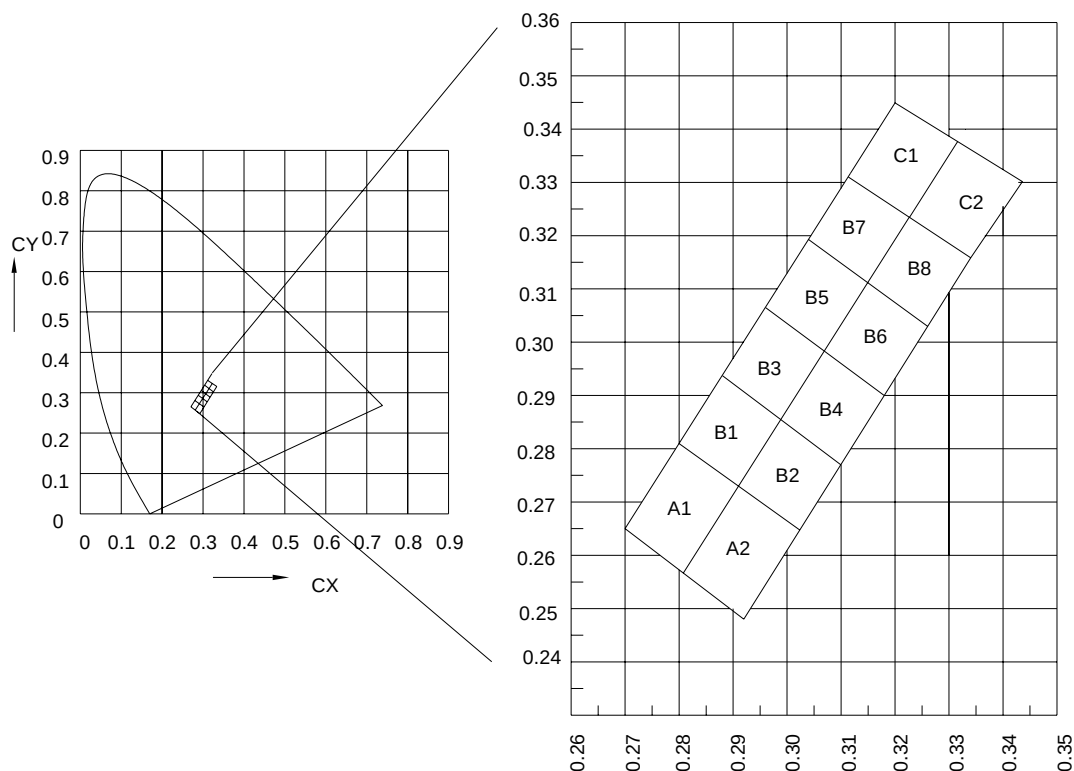
Chromaticity Coordinates Specifications for Bin Grading:

COLOR RANKS (IF=20mA, Ta=25°C)

BIN	RANK					BIN	RANK				
A1	X	0.27	0.28	0.291	0.281	B5	X	0.296	0.304	0.315	0.307
	Y	0.265	0.282	0.273	0.256		Y	0.307	0.319	0.311	0.298
A2	X	0.281	0.291	0.302	0.292	B6	X	0.307	0.315	0.326	0.318
	Y	0.256	0.273	0.265	0.248		Y	0.298	0.311	0.303	0.29
B1	X	0.28	0.288	0.299	0.291	B7	X	0.304	0.312	0.323	0.315
	Y	0.282	0.294	0.286	0.273		Y	0.319	0.331	0.323	0.311
B2	X	0.291	0.299	0.31	0.302	B8	X	0.315	0.323	0.334	0.326
	Y	0.273	0.286	0.277	0.265		Y	0.311	0.323	0.315	0.303
B3	X	0.288	0.296	0.307	0.299	C1	X	0.312	0.322	0.333	0.323
	Y	0.294	0.307	0.298	0.286		Y	0.331	0.348	0.34	0.323
B4	X	0.299	0.307	0.318	0.31	C2	X	0.323	0.333	0.344	0.334
	Y	0.286	0.298	0.29	0.277		Y	0.323	0.34	0.332	0.315

Note: X,Y Tolerance each Bin limit is ± 0.01 .

Chromaticity Coordinates & Bin grading diagram:



PRECAUTION IN USE

Storage

Recommended storage environment

Temperature: 5°C ~ 30°C (41°F ~ 86°F)

Humidity: 60% RH Max.

Use within 7 days after opening of sealed vapor/ESD barrier bags.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

Fold the opened bag firmly and keep in dry environment.

Soldering

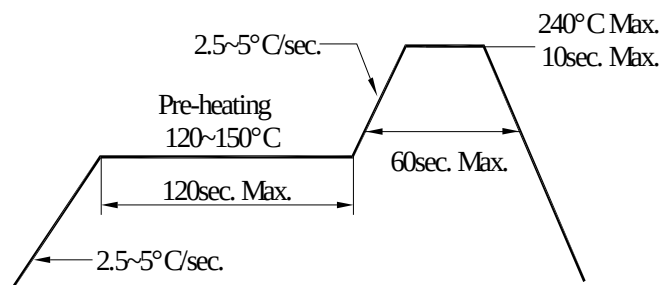
Reflow Soldering			Hand Soldering	
	Lead Solder	Lead – free Solder		
Pre-heat	120~150°C	180~200°C	Temperature	350°C Max.
Pre-heat time	120sec. Max.	120sec. Max.	Soldering time	3sec. Max. (one time only)
Peak temperature	240°C Max.	260°C Max.		
Soldering time	10sec. Max.	10sec. Max.		
Condition	refer to Temperature- profile 1	refer to Temperature- profile 2		

*After reflow soldering rapid cooling should be avoided.

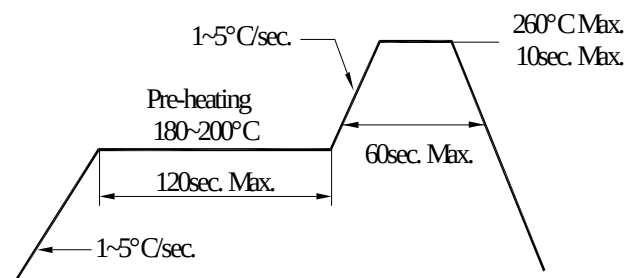
[Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.

< 1 : Lead Solder >

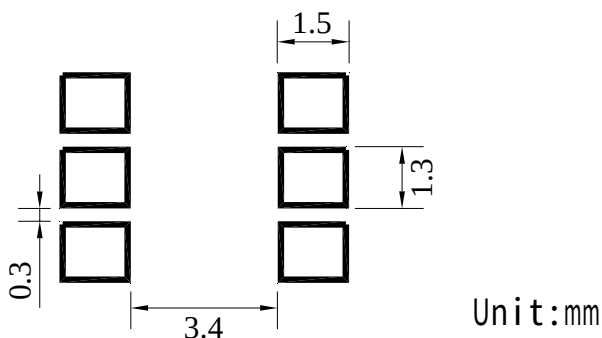


< 2 : Lead-free Solder >



[Recommended soldering pad design]

Use the following conditions shown in the figure.



Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound

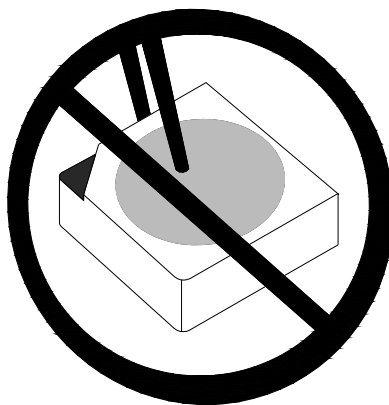


Figure 1

In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

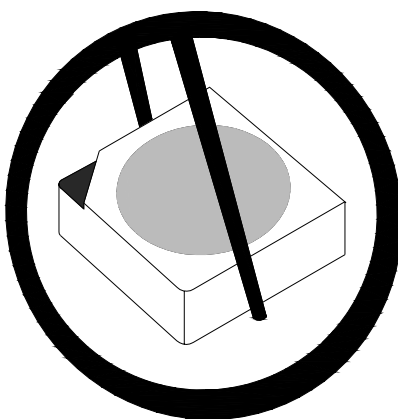
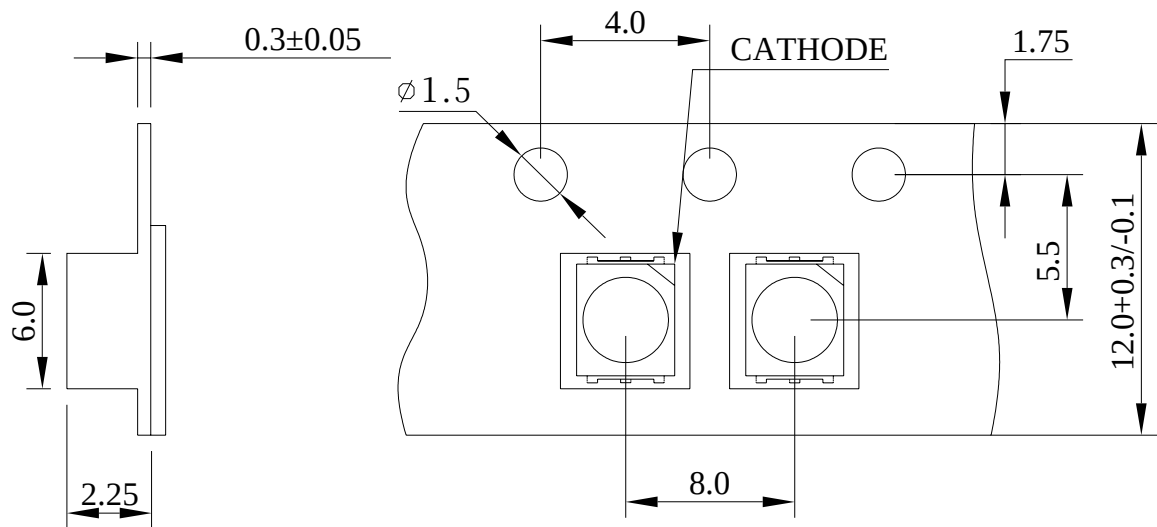


Figure 2

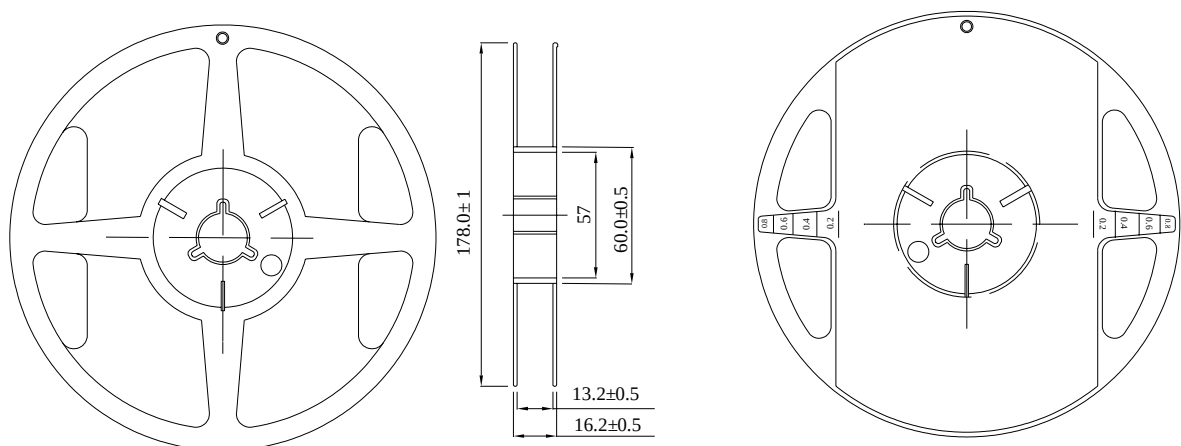
When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

Dimensions for Tape



Dimensions for Reel



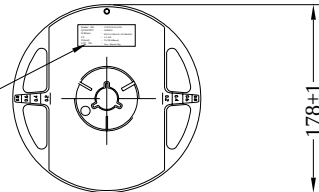
Notes:

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- 2.Specifications are subject to change without notice.

Packing

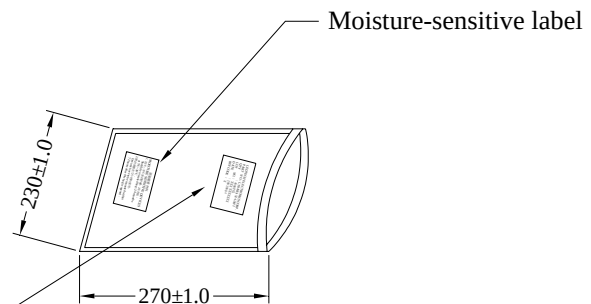
REEL
QUANTITY: 1,000 PCS

LEDTECH ELECTRONICS CORP.
PART NO :LTXXXX-XX
Q'TY : PCS
LOT NO :XXXXXXXXXX
DATE :
BIN CODE:



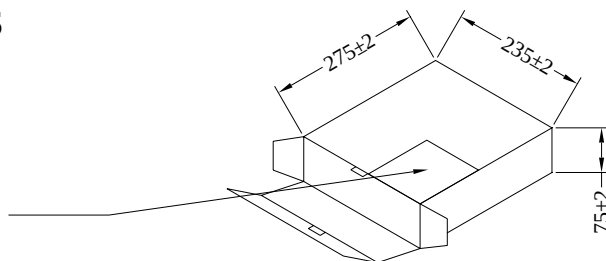
BAG
QUANTITY: 1,000 PCS

LEDTECH ELECTRONICS CORP.
PART NO :LTXXXX-XX
Q'TY : PCS
LOT NO :XXXXXXXXXX
DATE :
BIN CODE:



INSIDE BOX
QUANTITY: 4 BAGS
TOTAL: 4,000 PCS

LEDTECH ELECTRONICS CORP.
PART NO :LTXXXX-XX
Q'TY : PCS
LOT NO :XXXXXXXXXX
DATE :
BIN CODE:



Notes:

- 1.All dimensions are in mm, tolerance is ± 2.0 mm unless otherwise noted.
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